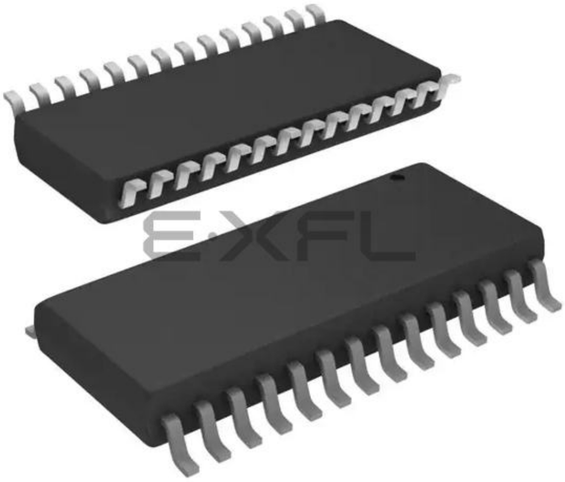


Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx110f016b-v-so

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUs

> **Note:** This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX 28/36/44-pin Family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 “Decoupling Capacitors”**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 “Decoupling Capacitors”**)
- VCAP pin (see **2.3 “Capacitor on Internal Voltage Regulator (VCAP)”**)
- $\overline{\text{MCLR}}$ pin (see **2.4 “Master Clear (MCLR) Pin”**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **2.5 “ICSP Pins”**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.7 “External Oscillator Pins”**)

The following pins may be required:

- VREF+/VREF- pins – used when external voltage reference for the ADC module is implemented

> **Note:** The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

REGISTER 4-4: BMXDUPBA: DATA RAM USER PROGRAM BASE ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0
	BMXDUPBA<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	BMXDUPBA<7:0>							

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15-10 **BMXDUPBA<15:10>:** DRM User Program Base Address bits

When non-zero, the value selects the relative base address for User mode program space in RAM, BMXDUPBA must be greater than BMXDUDBA.

bit 9-0 **BMXDUPBA<9:0>:** Read-Only bits

This value is always ‘0’, which forces 1 KB increments

Note 1: At Reset, the value in this register is forced to zero, which causes all of the RAM to be allocated to Kernal mode data usage.

2: The value in this register must be less than or equal to BMXDRMSZ.

8.0 OSCILLATOR CONFIGURATION

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 6. "Oscillator Configuration"** (DS60001112), which is available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32MX1XX/2XX 28/36/44-pin Family oscillator system has the following modules and features:

- Four external and internal oscillator options as clock sources
- On-Chip PLL with user-selectable input divider, multiplier and output divider to boost operating frequency on select internal and external oscillator sources
- On-Chip user-selectable divisor postscaler on select oscillator sources
- Software-controllable switching between various clock sources
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Dedicated On-Chip PLL for USB peripheral

A block diagram of the oscillator system is provided in Figure 8-1.

9.0 DIRECT MEMORY ACCESS (DMA) CONTROLLER

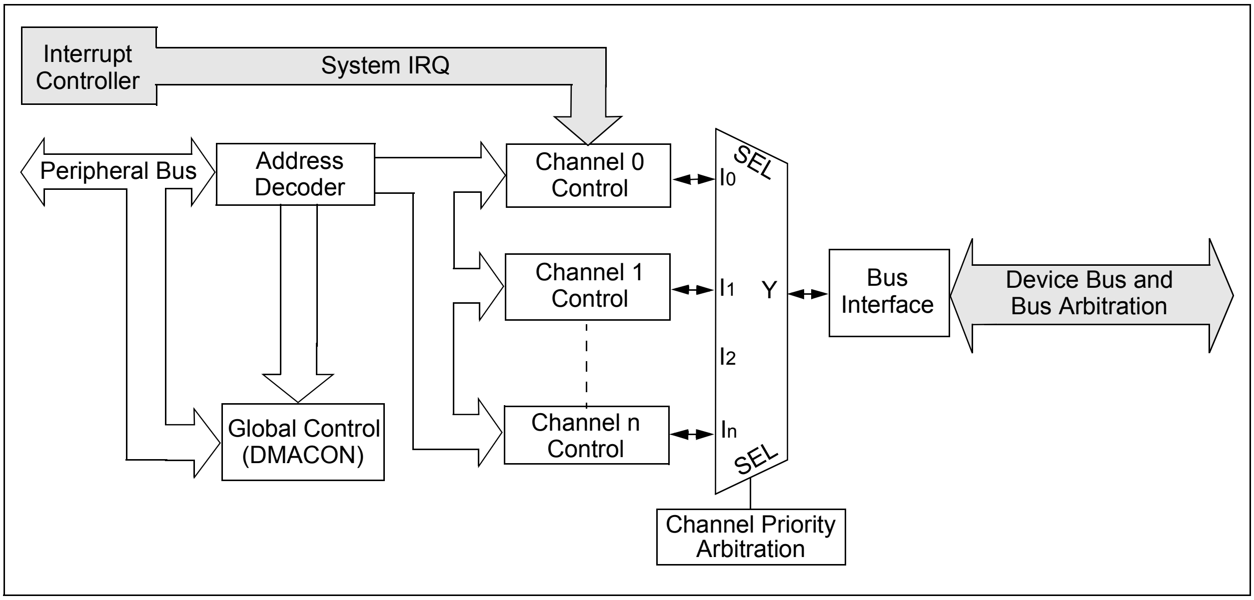
> **Note:** This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 31. "Direct Memory Access (DMA) Controller"** (DS60001117), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 Direct Memory Access (DMA) controller is a bus master module useful for data transfers between different devices without CPU intervention. The source and destination of a DMA transfer can be any of the memory mapped modules existent in the PIC32, such as Peripheral Bus devices: SPI, UART, PMP, etc., or memory itself. Figure 9-1 show a block diagram of the DMA Controller module.

The DMA Controller module has the following key features:

- Four identical channels, each featuring:
  - Auto-increment source and destination address registers
  - Source and destination pointers
  - Memory to memory and memory to peripheral transfers
- Automatic word-size detection:
  - Transfer granularity, down to byte level
  - Bytes need not be word-aligned at source and destination
- Fixed priority channel arbitration
- Flexible DMA channel operating modes:
  - Manual (software) or automatic (interrupt) DMA requests
  - One-Shot or Auto-Repeat Block Transfer modes
  - Channel-to-channel chaining
- Flexible DMA requests:
  - A DMA request can be selected from any of the peripheral interrupt sources
  - Each channel can select any (appropriate) observable interrupt as its DMA request source
  - A DMA transfer abort can be selected from any of the peripheral interrupt sources
  - Pattern (data) match transfer termination
- Multiple DMA channel status interrupts:
  - DMA channel block transfer complete
  - Source empty or half empty
  - Destination full or half full
  - DMA transfer aborted due to an external event
  - Invalid DMA address generated
- DMA debug support features:
  - Most recent address accessed by a DMA channel
  - Most recent DMA channel to transfer data
- CRC Generation module:
  - CRC module can be assigned to any of the available channels
  - CRC module is highly configurable

FIGURE 9-1: DMA BLOCK DIAGRAM



REGISTER 9-12: DCHxSSIZ: DMA CHANNEL ‘x’ SOURCE SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<7:0>							

Legend:
R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’
-n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **CHSSIZ<15:0>:** Channel Source Size bits

`1111111111111111` = 65,535 byte source size
•
•
•
`0000000000000010` = 2 byte source size
`0000000000000001` = 1 byte source size
`0000000000000000` = 65,536 byte source size

REGISTER 9-13: DCHxDSIZ: DMA CHANNEL ‘x’ DESTINATION SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<7:0>							

Legend:
R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’
-n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **CHDSIZ<15:0>:** Channel Destination Size bits

`1111111111111111` = 65,535 byte destination size
•
•
•
`0000000000000010` = 2 byte destination size
`0000000000000001` = 1 byte destination size
`0000000000000000` = 65,536 byte destination size

REGISTER 9-16: DCHxCSIZ: DMA CHANNEL ‘x’ CELL-SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHCSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHCSIZ<7:0>							

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **CHCSIZ<15:0>:** Channel Cell Size bits
`1111111111111111` = 65,535 bytes transferred on an event
•
•
•
`0000000000000010` = 2 bytes transferred on an event
`0000000000000001`= 1 byte transferred on an event
`0000000000000000` = 65,536 bytes transferred on an event

REGISTER 9-17: DCHxCPTR: DMA CHANNEL ‘x’ CELL POINTER REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHCPTR<15:8>							
7:0	R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
	CHCPTR<7:0>							

Legend:
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘`0`’

bit 15-0 **CHCPTR<15:0>:** Channel Cell Progress Pointer bits
`1111111111111111` = 65,535 bytes have been transferred since the last event
•
•
•
`0000000000000001` = 1 byte has been transferred since the last event
`0000000000000000` = 0 bytes have been transferred since the last event

Note: When in Pattern Detect mode, this register is reset on a pattern detect.

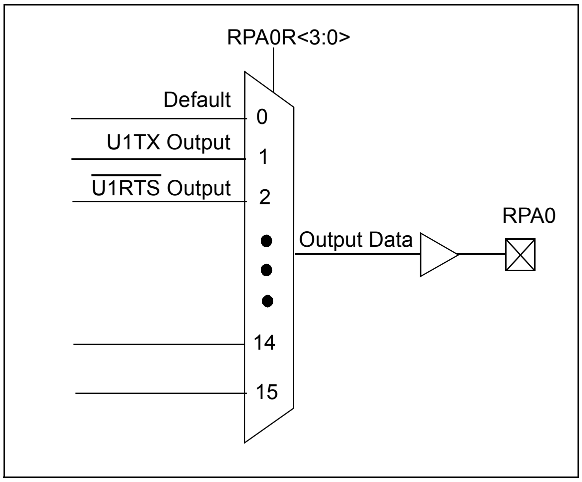
NOTES:

11.3.5 OUTPUT MAPPING

In contrast to inputs, the outputs of the PPS options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPnR registers (Register 11-2) are used to control output mapping. Like the [*pin name*]R registers, each register contains sets of 4 bit fields. The value of the bit field corresponds to one of the peripherals, and that peripheral's output is mapped to the pin (see Table 11-2 and Figure 11-3).

A null output is associated with the output register reset value of '`0`'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 11-3: EXAMPLE OF MULTIPLEXING OF REMAPPABLE OUTPUT FOR RPA0



11.3.6 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. PIC32 devices include two features to prevent alterations to the peripheral map:

- Control register lock sequence
- Configuration bit select lock

11.3.6.1 Control Register Lock Sequence

Under normal operation, writes to the RPnR and [*pin name*]R registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the Configuration bit, IOLOCK (CFGCON<13>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear the IOLOCK bit, an unlock sequence must be executed. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

11.3.6.2 Configuration Bit Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPnR and [*pin name*]R registers. The Configuration bit, IOL1WAY (DEVCFG3<29>), blocks the IOLOCK bit from being cleared after it has been set once. If IOLOCK remains set, the register unlock procedure does not execute, and the PPS control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session.

NOTES:

REGISTER 20-2: PMMODE: PARALLEL PORT MODE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
	BUSY	IRQM<1:0>		INCM<1:0>		—	MODE<1:0>	
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	WAITB<1:0>[(1)]		WAITM<3:0>[(1)]				WAITE<1:0>[(1)]	

Legend:
R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR
‘1’ = Bit is set
‘0’ = Bit is cleared
x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15 **BUSY:** Busy bit (Master mode only)
1 = Port is busy
0 = Port is not busy

bit 14-13 **IRQM<1:0>:** Interrupt Request Mode bits
11 = Reserved, do not use
10 = Interrupt generated when Read Buffer 3 is read or Write Buffer 3 is written (Buffered PSP mode) or on a read or write operation when PMA<1:0> =11 (Addressable Slave mode only)
01 = Interrupt generated at the end of the read/write cycle
00 = No Interrupt generated

bit 12-11 **INCM<1:0>:** Increment Mode bits
11 = Slave mode read and write buffers auto-increment (MODE<1:0> = 00 only)
10 = Decrement ADDR<10:2> and ADDR<14> by 1 every read/write cycle(2)
01 = Increment ADDR<10:2> and ADDR<14> by 1 every read/write cycle(2)
00 = No increment or decrement of address

bit 10 **Unimplemented:** Read as ‘0’

bit 9-8 **MODE<1:0>:** Parallel Port Mode Select bits
11 = Master mode 1 (PMCS1, PMRD/PMWR, PMENB, PMA<x:0>, and PMD<7:0>)
10 = Master mode 2 (PMCS1, PMRD, PMWR, PMA<x:0>, and PMD<7:0>)
01 = Enhanced Slave mode, control signals (PMRD, PMWR, PMCS1, PMD<7:0>, and PMA<1:0>)
00 = Legacy Parallel Slave Port, control signals (PMRD, PMWR, PMCS1, and PMD<7:0>)

bit 7-6 **WAITB<1:0>:** Data Setup to Read/Write Strobe Wait States bits(1)
11 = Data wait of 4 TPB; multiplexed address phase of 4 TPB
10 = Data wait of 3 TPB; multiplexed address phase of 3 TPB
01 = Data wait of 2 TPB; multiplexed address phase of 2 TPB
00 = Data wait of 1 TPB; multiplexed address phase of 1 TPB (default)

bit 5-2 **WAITM<3:0>:** Data Read/Write Strobe Wait States bits(1)
1111 = Wait of 16 TPB
•
•
•
0001 = Wait of 2 TPB
0000 = Wait of 1 TPB (default)

Note 1: Whenever WAITM<3:0> = 0000, WAITB and WAITE bits are ignored and forced to 1 TPBCLK cycle for a write operation; WAITB = 1 TPBCLK cycle, WAITE = 0 TPBCLK cycles for a read operation.

2: Address bit A14 is not subject to auto-increment/decrement if configured as Chip Select CS1.

23.1 Comparator Control Registers

TABLE 23-1: COMPARATOR REGISTER MAP

Virtual Address (BF80_#)	Register Name[1]	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
A000	CM1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	`0000`
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		`00C3`
A010	CM2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	`0000`
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		`00C3`
A020	CM3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	`0000`
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		`00C3`
A060	CMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	`0000`
		15:0	—	—	SIDL	—	—	—	—	—	—	—	—	—	—	C3OUT	C2OUT	C1OUT	`0000`

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET and INV Registers”** for more information.

26.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have effect and read values are invalid.

To disable a peripheral, the associated PMDx bit must be set to '1'. To enable a peripheral, the associated PMDx bit must be cleared (default). See Table 26-1 for more information.

Note: Disabling a peripheral module while it's ON bit is set, may result in undefined behavior. The ON bit for the associated peripheral module must be cleared prior to disable a module via the PMDx bits.

TABLE 26-1: PERIPHERAL MODULE DISABLE BITS AND LOCATIONS

Peripheral[1]	PMDx bit Name[1]	Register Name and Bit Location
ADC1	AD1MD	PMD1<0>
CTMU	CTMUMD	PMD1<8>
Comparator Voltage Reference	CVRMD	PMD1<12>
Comparator 1	CMP1MD	PMD2<0>
Comparator 2	CMP2MD	PMD2<1>
Comparator 3	CMP3MD	PMD2<2>
Input Capture 1	IC1MD	PMD3<0>
Input Capture 2	IC2MD	PMD3<1>
Input Capture 3	IC3MD	PMD3<2>
Input Capture 4	IC4MD	PMD3<3>
Input Capture 5	IC5MD	PMD3<4>
Output Compare 1	OC1MD	PMD3<16>
Output Compare 2	OC2MD	PMD3<17>
Output Compare 3	OC3MD	PMD3<18>
Output Compare 4	OC4MD	PMD3<19>
Output Compare 5	OC5MD	PMD3<20>
Timer1	T1MD	PMD4<0>
Timer2	T2MD	PMD4<1>
Timer3	T3MD	PMD4<2>
Timer4	T4MD	PMD4<3>
Timer5	T5MD	PMD4<4>
UART1	U1MD	PMD5<0>
UART2	U2MD	PMD5<1>
SPI1	SPI1MD	PMD5<8>
SPI2	SPI2MD	PMD5<9>
I2C1	I2C1MD	PMD5<16>
I2C2	I2C2MD	PMD5<17>
USB[2]	USBMD	PMD5<24>
RTCC	RTCCMD	PMD6<0>
Reference Clock Output	REFOMD	PMD6<1>
PMP	PMPMD	PMD6<16>

Note 1: Not all modules and associated PMDx bits are available on all devices. See **TABLE 1: "PIC32MX1XX 28/36/44-Pin General Purpose Family Features"** and **TABLE 2: "PIC32MX2XX 28/36/44-pin USB Family Features"** for the lists of available peripherals.

2: The module must not be busy after clearing the associated ON bit and prior to setting the USBMD bit.

29.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

29.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

29.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

TABLE 30-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical$^{(1)}$**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O Pins with PMP	VSS	—	0.15 VDD	V	
		I/O Pins	VSS	—	0.2 VDD	V	
DI18		SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled **(Note 4)**
DI19		SDAx, SCLx	VSS	—	0.8	V	SMBus enabled **(Note 4)**
	VIH	**Input High Voltage**					
DI20		I/O Pins not 5V-tolerant$^{(5)}$	0.65 VDD	—	VDD	V	**(Note 4,6)**
		I/O Pins 5V-tolerant with PMP$^{(5)}$	0.25 VDD + 0.8V	—	5.5	V	**(Note 4,6)**
		I/O Pins 5V-tolerant$^{(5)}$	0.65 VDD	—	5.5	V	
DI28		SDAx, SCLx	0.65 VDD	—	5.5	V	SMBus disabled **(Note 4,6)**
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤ VPIN ≤ 5.5 **(Note 4,6)**
DI30	ICNPU	**Change Notification Pull-up Current**	—	—	-50	µA	VDD = 3.3V, VPIN = VSS **(Note 3,6)**
DI31	ICNPD	**Change Notification Pull-down Current$^{(4)}$**	—	—	-50	µA	VDD = 3.3V, VPIN = VDD
	IIL	**Input Leakage Current (Note 3)**					
DI50		I/O Ports	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{\text{MCLR}}^{(2)}$	—	—	±1	µA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **"Pin Diagrams"** section for the 5V-tolerant pins.

6: The VIH specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic "high" internally to the PIC32 device, provided that the external load does not exceed the minimum value of ICNPU. For External "input" logic inputs that require a pull-up source, to guarantee the minimum VIH of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

TABLE 30-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory(3)					
D130	EP	Cell Endurance	20,000	—	—	E/W	—
D131	VPR	VDD for Read	2.3	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	2.3	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	TWW	Word Write Cycle Time	—	411	—	FRC Cycles	See **Note 4**
D136	TRW	Row Write Cycle Time	—	6675	—		See **Note 2,4**
D137	TPE	Page Erase Cycle Time	—	20011	—		See **Note 4**
	TCE	Chip Erase Cycle Time	—	80180	—		See **Note 4**

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the *“PIC32 Flash Programming Specification”* (DS60001145) for operating conditions during programming and erase cycles.

4: This parameter depends on FRC accuracy (See Table 30-19) and FRC tuning values (See Register 8-2).

TABLE 30-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**[(1)]	**Max.**	**Units**	**Conditions**
IM10	$T_{LO:SCL}$	Clock Low Time	100 kHz mode	T_{PB} * (BRG + 2)	—	µs	—
			400 kHz mode	T_{PB} * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	T_{PB} * (BRG + 2)	—	µs	—
IM11	$T_{HI:SCL}$	Clock High Time	100 kHz mode	T_{PB} * (BRG + 2)	—	µs	—
			400 kHz mode	T_{PB} * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	T_{PB} * (BRG + 2)	—	µs	—
IM20	$T_{F:SCL}$	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	C_B is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 C_B	300	ns	
			1 MHz mode **(Note 2)**	—	100	ns	
IM21	$T_{R:SCL}$	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	C_B is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 C_B	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	$T_{SU:DAT}$	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	$T_{HD:DAT}$	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 2)**	0	0.3	µs	
IM30	$T_{SU:STA}$	Start Condition Setup Time	100 kHz mode	T_{PB} * (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	T_{PB} * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	T_{PB} * (BRG + 2)	—	µs	
IM31	$T_{HD:STA}$	Start Condition Hold Time	100 kHz mode	T_{PB} * (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	T_{PB} * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	T_{PB} * (BRG + 2)	—	µs	
IM33	$T_{SU:STO}$	Stop Condition Setup Time	100 kHz mode	T_{PB} * (BRG + 2)	—	µs	—
			400 kHz mode	T_{PB} * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	T_{PB} * (BRG + 2)	—	µs	
IM34	$T_{HD:STO}$	Stop Condition Hold Time	100 kHz mode	T_{PB} * (BRG + 2)	—	ns	—
			400 kHz mode	T_{PB} * (BRG + 2)	—	ns	
			1 MHz mode **(Note 2)**	T_{PB} * (BRG + 2)	—	ns	

Note 1: BRG is the value of the I^{2}C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

31.1 DC Characteristics

TABLE 31-1: OPERATING MIPS VS. VOLTAGE

Characteristic	V_{DD} Range (in Volts)[1]	Temp. Range (in °C)	Max. Frequency
			PIC32MX1XX/2XX 28/36/44-pin Family
MDC5	2.3-3.6V	-40°C to +85°C	50 MHz

Note 1: Overall functional device operation at $V_{BORMIN} < V_{DD} < V_{DDMIN}$ is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below V_{DDMIN}. Refer to parameter BO10 in Table 30-11 for BOR values.

TABLE 31-2: DC CHARACTERISTICS: OPERATING CURRENT (I_{DD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial	
Parameter No.	**Typical[3]**	**Max.**	**Units**	**Conditions**
Operating Current (I_{DD}) (Note 1, 2)				
MDC24	25	37	mA	50 MHz

Note 1: A device's I_{DD} supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

2: The test conditions for I_{DD} measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU, Program Flash, and SRAM data memory are operational, SRAM data memory Wait states = `1`
- No peripheral modules are operating, (ON bit = `0`), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR} = V_{DD}$
- CPU executing `while(1)` statement from Flash

3: RTCC and JTAG are disabled

4: Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 31-3: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial	
Parameter No.	**Typical[(2)]**	**Max.**	**Units**	**Conditions**
Idle Current (IIDLE): Core Off, Clock on Base Current (Note 1)				
MDC34a	8	13	mA	50 MHz

Note 1: The test conditions for IIDLE current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Idle mode (CPU core Halted), and SRAM data memory Wait states = `1`
- No peripheral modules are operating, (ON bit = `0`), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial		
Param. No.	**Typical[(2)]**	**Max.**	**Units**	**Conditions**	
Power-Down Current (IPD) (Note 1)					
MDC40k	10	25	µA	-40°C	Base Power-Down Current
MDC40n	250	500	µA	+85°C	
Module Differential Current					
MDC41e	10	55	µA	3.6V	Watchdog Timer Current: ΔIWDT **(Note 3)**
MDC42e	23	55	µA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔIRTCC **(Note 3)**
MDC43d	1100	1300	µA	3.6V	ADC: ΔIADC **(Notes 3,4)**

Note 1: The test conditions for IPD current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = `1`
- No peripheral modules are operating, (ON bit = `0`), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD
- RTCC and JTAG are disabled

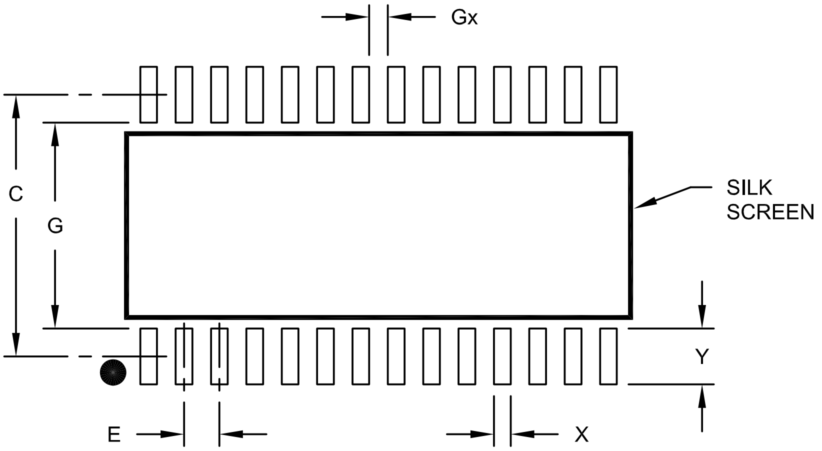
2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

APPENDIX A: REVISION HISTORY

Revision A (May 2011)

This is the initial released version of this document.

Revision B (October 2011)

The following two global changes are included in this revision:

- All packaging references to VLAP have been changed to VTLA throughout the document
- All references to VCORE have been removed
- All occurrences of the ASCL1, ASCL2, ASDA1, and ASDA2 pins have been removed
- V-temp temperature range (-40ºC to +105ºC) was added to all electrical specification tables

This revision includes the addition of the following devices:

- PIC32MX130F064B
- PIC32MX130F064C
- PIC32MX130F064D
- PIC32MX150F128B
- PIC32MX150F128C
- PIC32MX150F128D
- PIC32MX230F064B
- PIC32MX230F064C
- PIC32MX230F064D
- PIC32MX250F128B
- PIC32MX250F128C
- PIC32MX250F128D

Text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in Table A-1.

TABLE A-1: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog**”**	Split the existing Features table into two: PIC32MX1XX General Purpose Family Features (Table 1) and PIC32MX2XX USB Family Features (Table 2). Added the SPDIP package reference (see Table 1, Table 2, and **“Pin Diagrams”**). Added the new devices to the applicable pin diagrams. Changed PGED2 to PGED1 on pin 35 of the 36-pin VTLA diagram for PIC32MX220F032C, PIC32MX220F016C, PIC32MX230F064C, and PIC32MX250F128C devices.
1.0 “Device Overview”	Added the SPDIP package reference and updated the pin number for AN12 for 44-pin QFN devices in the Pinout I/O Descriptions (see Table 1-1). Added the PGEC4/PGED4 pin pair and updated the C1INA-C1IND and C2INA-C2IND pin numbers for 28-pin SSOP/SPDIP/SOIC devices in the Pinout I/O Descriptions (see Table 1-1).
2.0 “Guidelines for Getting Started with 32-bit Microcontrollers”	Updated the Recommended Minimum Connection diagram (see Figure 2-1).